Ref #	Hits	Search Query	DBs	Default Operator	Plurals
L1	3618579	(semiconductor die chip ic (integrated adj circuit))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON
L2	49061	(leadframe (lead adj frame)) same 1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON
L3	8668	(paddle ((chip die) adj4 (pad paddle))) same 2	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON
L4	5031	wire same 3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON
L5	4979	lead and 4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON
L6	2729	(support supporting supportable supported) and 5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON
L7	2513	(package packaging packaged) and 6	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON
L8	2334	(encapsulating encapsulate encapsulant encase encapsulated resin epoxy) and 7	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON

			OR	ON
L9	1976744	(substrate carrier board ((printed wiring cirucit) adj4 board)) and "9"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON
L10	1948	(substrate carrier board ((printed wiring cirucit) adj4 board)) and 8	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON